

November 2013

FDMS039N08B

N-Channel PowerTrench[®] MOSFET 80 V, 100 A, 3.9 m Ω

Features

- $R_{DS(on)}$ = 3.2 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 50 A
- Low FOM R_{DS(on)} *Q_G
- Low Reverse Recovery Charge, Q_{rr =} 80 nC
- Soft Reverse Recovery Body Diode
- Enables Highly Efficiency in Synchronous Rectification
- · Fast Switching Speed
- · 100% UIL Tested
- · RoHS Compliant

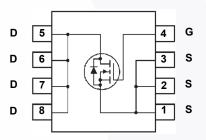
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advance PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- · Battery Protection Circuit
- · Motor drives and Uninterruptible Power Supplies





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter			Unit
V_{DSS}	Drain to Source Voltage			80	V
V_{GSS}	Gate to Source Voltage			±20	V
	Drain Current	- Continuous (T _C = 25°C)		100	Α
'D	Diam Current	- Continuous (T _A = 25°C)	(Note 1a)	19.4	A
I _{DM}	Drain Current	Drain Current - Pulsed (Note 2)		400	Α
E _{AS}	Single Pulsed Avalanche Energy	Single Pulsed Avalanche Energy (Note 3)		240	mJ
В	Power Dissipation	$(T_C = 25^{\circ}C)$		104	W
P _D Power Dissipation	$(T_A = 25^{\circ}C)$	(Note 1a)	2.5	W	
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	FDMS039N08B	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	1.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. (Note 1a)	50	- 6/77

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS039N08B	FDMS039N08B	Power 56	13 "	12 mm	3000 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{V}$	80	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C	-	0.04	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 64 V, V _{GS} = 0 V	-	-	1	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$	-	3.2	3.9	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 50 A	-	100	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 40.V.V 0.V	-	5715	7600	pF
Coss	Output Capacitance	V _{DS} = 40 V, V _{GS} = 0 V f = 1 MHz		881	1170	pF
C _{rss}	Reverse Transfer Capacitance			15	-	pF
C _{oss} (er)	Engry Releted Output Capacitance	V _{DS} = 40 V, V _{GS} = 0 V	-	1646	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 40 V, I _D = 50 A	-	77	100	nC
Q _{gs}	Gate to Source Gate Charge	$V_{GS} = 0 \text{ V to } 10 \text{ V}$	-	34	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau		-	13	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	16	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1.2	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		-	42	94	ns
t _r	Turn-On Rise Time	$V_{DD} = 40 \text{ V}, I_{D} = 50 \text{ A}$	-	25	60	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_G = 4.7 \Omega$	-	48	106	ns
t _f	Turn-Off Fall Time	(Note 4)	-	17	44	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current	/ -	-	100	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	400	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 50 A	_	-	1.3	V
t _{rr}	Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_{SD} = 50 \text{ A}, V_{DD} = 40 \text{ A}$	40 V -	68	/	ns
Q _{rr}	Reverse Recovery Charge $dI_F/dt = 100 A/\mu s$	-	80	-	nC

Notes

TAR_{9,A} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{9,JC} is guaranteed by design while R_{9CA} is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



 b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Repetitive rating: pulse-width limited by maximum junction temperature.
- 3. L = 0.3 mH, I_{AS} = 40 A, starting T_J = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

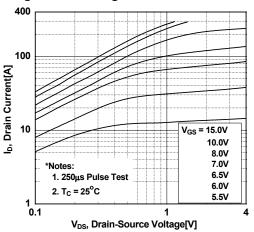


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

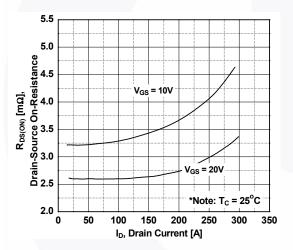


Figure 5. Capacitance Characteristics

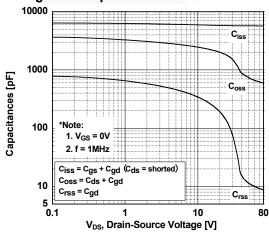


Figure 2. Transfer Characteristics

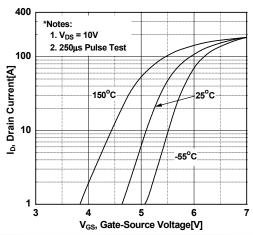


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

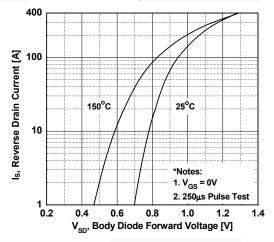
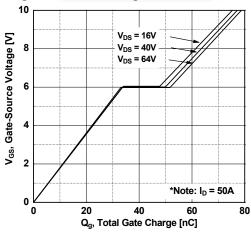


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

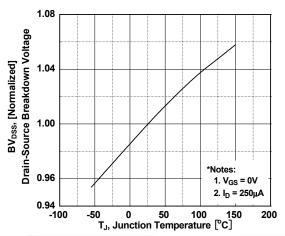


Figure 9. Maximum Safe Operating Area

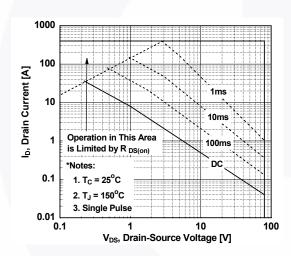


Figure 11. Unclamped Inductive Switching Capability

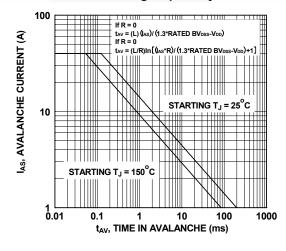


Figure 8. On-Resistance Variation vs. Temperature

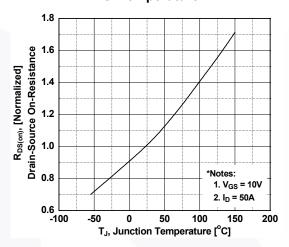


Figure 10. Maximum Drain Current vs. Case Temperature

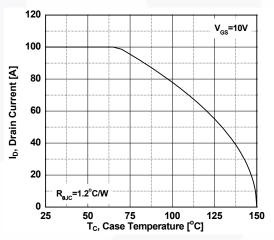
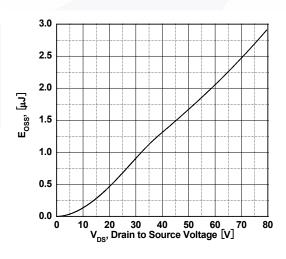


Figure 12. Eoss vs. Drain to Source Voltage



Typical Performance Characteristics (Continued)



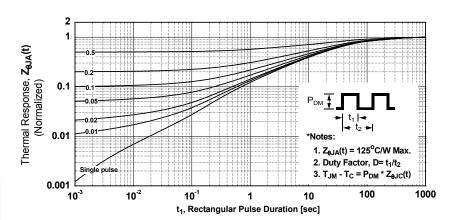


Figure 14. Gate Charge Test Circuit & Waveform

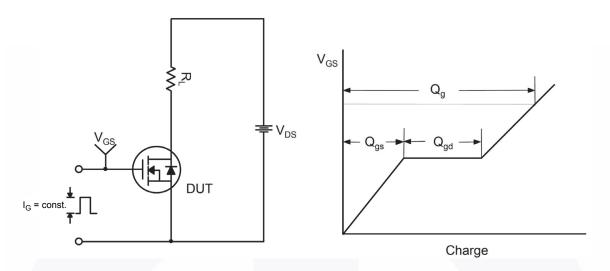


Figure 15. Resistive Switching Test Circuit & Waveforms

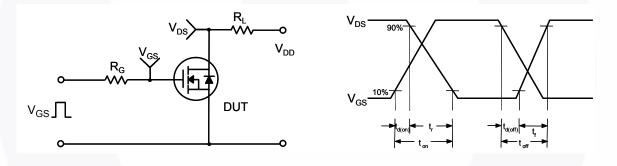
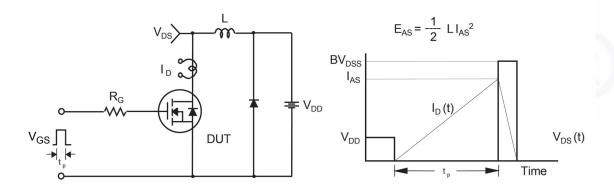


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms



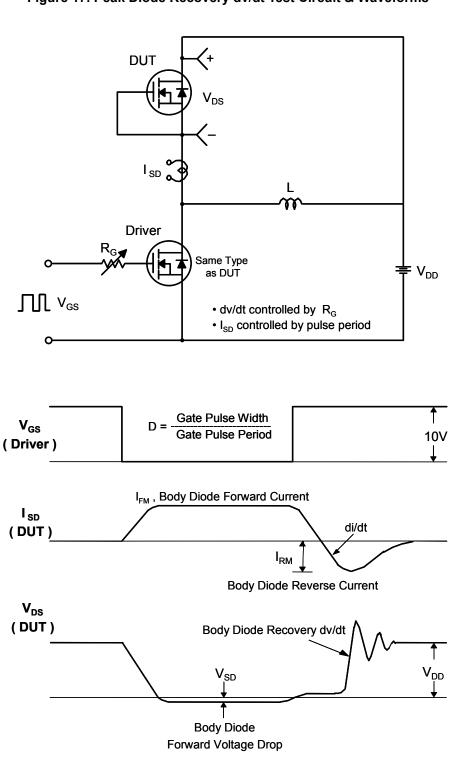


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechnical Dimensions

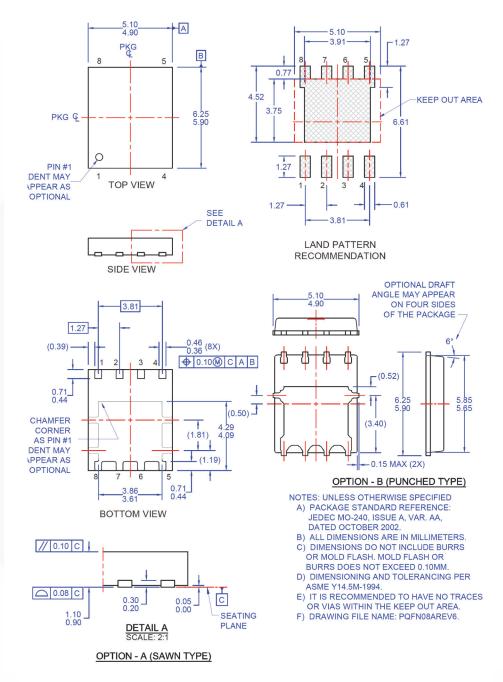


Figure 18. 8LD, PQFN, JEDEC MO-240 AA, 5.0X6.0MM

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